# **VHF/UHF Transistor**

## **NPN Silicon**

#### **Features**

- S and NSV Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	$V_{CEO}$	25	Vdc
Collector-Base Voltage	$V_{CBO}$	30	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	3.0	Vdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ heta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction to Ambient (Note 2)	$R_{ heta JA}$	417	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

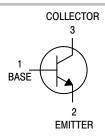
- 1.  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina



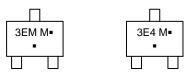
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#### **MARKING DIAGRAMS**



MMBTH10LT1G, NSVMMBTH10LT1G MMBTH10-04LT1G

3EM, 3E4= Specific Device Code

M = Date Code\*

Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBTH10LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
NSVMMBTH10LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBTH10-4LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBTH10LT3G, SMMBTH10-4LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•	•	-
Collector–Emitter Breakdown Voltage $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	25	_	-	Vdc
Collector–Base Breakdown Voltage (I <sub>C</sub> = 100 μAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	30	-	-	Vdc
Emitter–Base Breakdown Voltage $(I_E = 10 \mu Adc, I_C = 0)$	V <sub>(BR)EBO</sub>	3.0	-	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 25 Vdc, I <sub>E</sub> = 0)	Ісво	-	-	100	nAdc
Emitter Cutoff Current (V <sub>EB</sub> = 2.0 Vdc, I <sub>C</sub> = 0)	I <sub>EBO</sub>	-	_	100	nAdc
ON CHARACTERISTICS			•	•	-
DC Current Gain ( $I_C = 4.0$ mAdc, $V_{CE} = 10$ Vdc) MMBTH10LT1G, NSVMMBTH10LT1G MMBTH10-4LT1G, SMMBTH10-4LT3G	h <sub>FE</sub>	60 120	_ _	_ 240	-
Collector–Emitter Saturation Voltage (I <sub>C</sub> = 4.0 mAdc, I <sub>B</sub> = 0.4 mAdc)	V <sub>CE(sat)</sub>	_	_	0.5	Vdc
Base–Emitter On Voltage (I <sub>C</sub> = 4.0 mAdc, V <sub>CE</sub> = 10 Vdc)	V <sub>BE</sub>	-	-	0.95	Vdc
SMALL-SIGNAL CHARACTERISTICS			•		•
Current–Gain – Bandwidth Product (I <sub>C</sub> = 4.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 100 Mhz) MMBTH10LT1G, NSVMMBTH10LT1G MMBTH10–4LT1G, SMMBTH10–4LT3G	f <sub>T</sub>	650 800	_ _	_ _	MHz
Collector–Base Capacitance $(V_{CB}=10 \text{ Vdc}, I_E=0, f=1.0 \text{ MHz})$	C <sub>cb</sub>	-	-	0.7	pF
Common–Base Feedback Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>rb</sub>	-	-	0.65	pF
Collector Base Time Constant (I <sub>C</sub> = 4.0 mAdc, V <sub>CB</sub> = 10 Vdc, f = 31.8 MHz)	rb′C <sub>c</sub>	-	-	9.0	ps

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## **TYPICAL CHARACTERISTICS**

## **COMMON-BASE y PARAMETERS versus FREQUENCY**

 $(V_{CB} = 10 \text{ Vdc}, I_{C} = 4.0 \text{ mAdc}, T_{A} = 25^{\circ}\text{C})$ 

## yib, INPUT ADMITTANCE

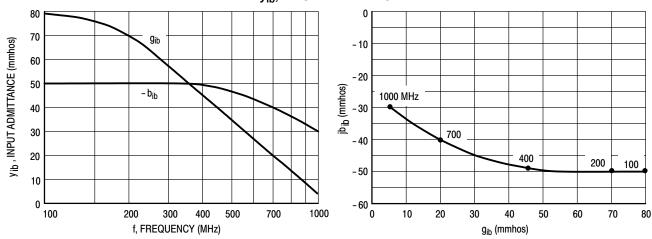


Figure 1. Rectangular Form

Figure 2. Polar Form

# y<sub>fb</sub>, FORWARD TRANSFER ADMITTANCE

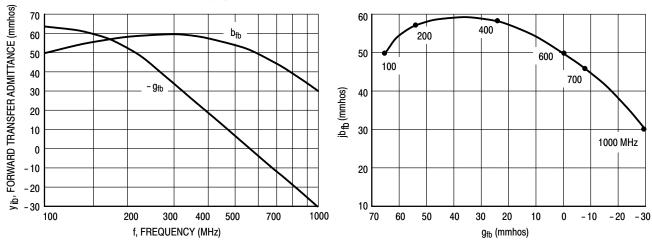


Figure 3. Rectangular Form

Figure 4. Polar Form

## **TYPICAL CHARACTERISTICS**

## **COMMON-BASE y PARAMETERS versus FREQUENCY**

 $(V_{CB} = 10 \text{ Vdc}, I_C = 4.0 \text{ mAdc}, T_A = 25^{\circ}\text{C})$ 

# y<sub>rb</sub>, REVERSE TRANSFER ADMITTANCE

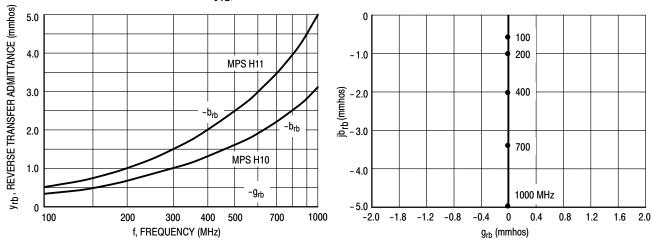


Figure 5. Rectangular Form

Figure 6. Polar Form

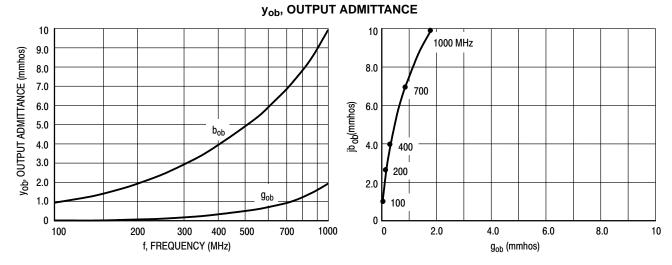
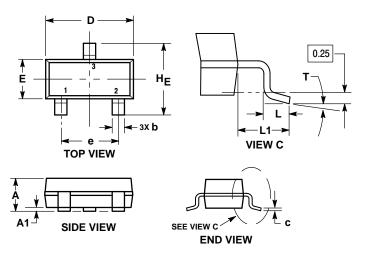


Figure 7. Rectangular Form

Figure 8. Polar Form

#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR** 



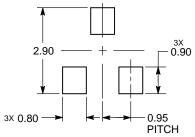
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	0°		10°	0°		10°

#### STYLE 6:

- PIN 1. BASE
  - **EMITTER**
  - COLLECTOR

#### **RECOMMENDED** SOLDERING FOOTPRINT\*



**DIMENSIONS: MILLIMETERS** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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